

## N-Channel Enhancement Mode MOSFET

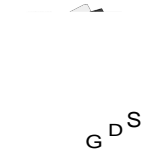
### Feature

- 80V/130A  
 $R_{DS(ON)} = 4\text{ m}\Omega(\text{typ.}) @ V_{GS} = 10\text{V}$
- 100% Avalanche Tested
- Reliable and Rugged
- Lead-Free and Green Devices Available (RoHS Compliant)

### Pin Description



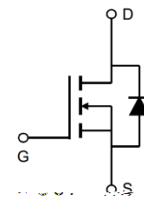
TO-220FB-3L



TO-263-2L



### Applications

- Switching application
- Power management for inverter systems
- Motor control



N-Channel MOSFET

### Ordering and Marking Information

 P <b>G050N08</b> XYMXXXXXX	 B <b>G050N08</b> XYMXXXXXX	Package Code P : TO-220FB-3L      B : TO-263-2L  Date Code XYMXXXXXX
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Note: HUAYI lead-free products contain molding compounds/die attach materials and 100% matte tin plate Termination finish; which are fully compliant with RoHS. HUAYI lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020 for MSL classification at lead-free peak reflow temperature. HUAYI defines “Green” to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

HUAYI reserves the right to make changes, corrections, enhancements, modifications, and improvements to this product and/or to this document at any time without notice.

# HYG050N08NS1P/B

## Absolute Maximum Ratings

Symbol	Parameter		Rating	Unit
<b>Common Ratings</b> (Tc=25°C Unless Otherwise Noted)				
V <sub>DSS</sub>	Drain-Source Voltage		80	V
V <sub>GSS</sub>	Gate-Source Voltage		20	V
T <sub>J</sub>	Junction Temperature Range		-55 to 175	°C
T <sub>STG</sub>	Storage Temperature Range		-55 to 175	°C
I <sub>S</sub>	Source Current-Continuous(Body Diode)	Tc=25°C	130	A
<b>Mounted on Large Heat Sink</b>				
I <sub>DM</sub>	Pulsed Drain Current *	Tc=25°C	450	A
I <sub>D</sub>	Continuous Drain Current	Tc=25°C	130	A
		Tc=100°C	92	A
P <sub>D</sub>	Maximum Power Dissipation	Tc=25°C	187.5	W
		Tc=100°C	93.7	W
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case		0.8	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient **		62.5	°C/W
E <sub>AS</sub>	Single Pulsed-Avalanche Energy ***	L=0.3mH	244	mJ

Note: \* Repetitive rating pulse width limited by max.junction temperature. J<sub>AVT</sub>

## Electrical Characteristics (Cont.) (Tc =25°C Unless Otherwise Noted)

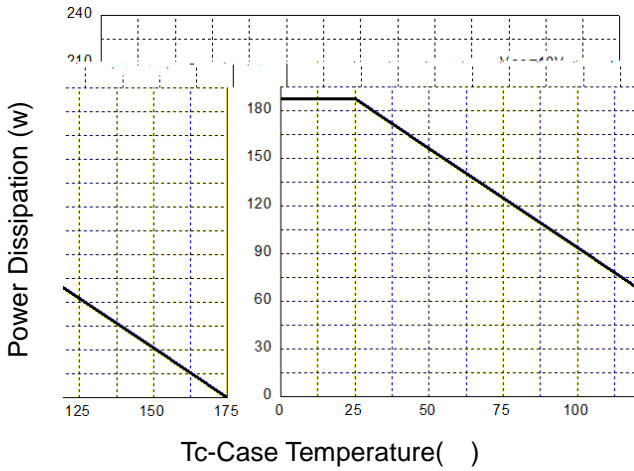
Symbol	Parameter	Test Conditions	HYG050N08NS1			Unit
			Min	Typ.	Max	
<b>Dynamic Characteristics</b>						
R <sub>G</sub>	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz	-	2.6	-	Ω
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> = 25V, Frequency=1.0MHz	-	4280	-	pF
C <sub>oss</sub>	Output Capacitance					
C <sub>rss</sub>	Reverse Transfer Capacitance					
t <sub>d(ON)</sub>	Turn-on Delay Time	V <sub>DD</sub> = 40V, R <sub>G</sub> =4Ω, I <sub>DS</sub> = 50A, V <sub>GS</sub> = 10V	-	17	-	ns
T <sub>r</sub>	Turn-on Rise Time					
t <sub>d(OFF)</sub>	Turn-off Delay Time					
T <sub>f</sub>	Turn-off Fall Time					
<b>Gate Charge Characteristics</b>						
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = 64V, V <sub>GS</sub> = 10V, I <sub>DS</sub> = 50A	-	68	-	nC
Q <sub>gs</sub>	Gate-Source Charge					
Q <sub>gd</sub>	Gate-Drain Charge					

Note: \*Pulse test pulse width ≤ 300us duty cycle ≤ 2%

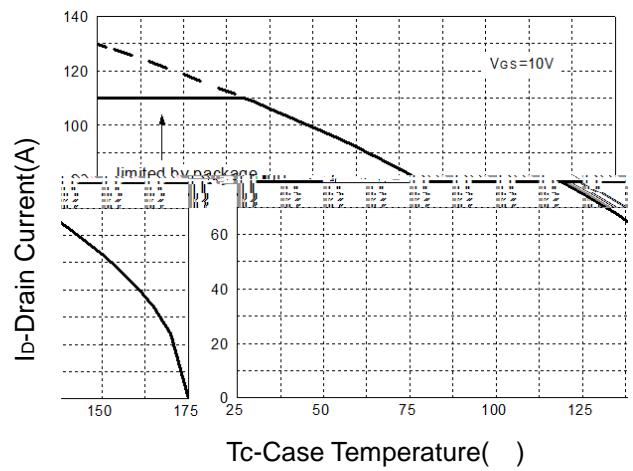
# HYG050N08NS1P/B

## Typical Operating Characteristics

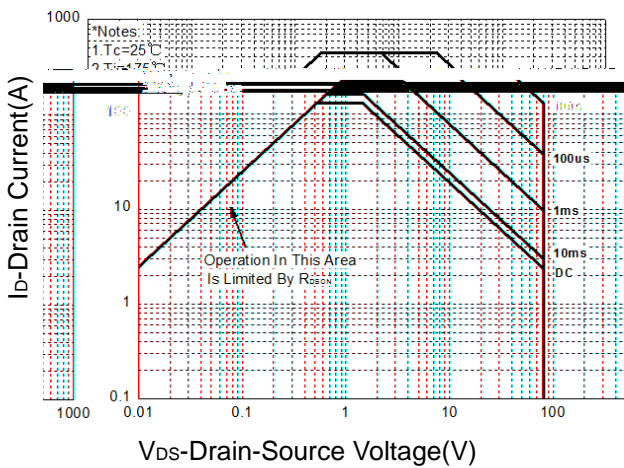
**Figure 1: Power Dissipation**



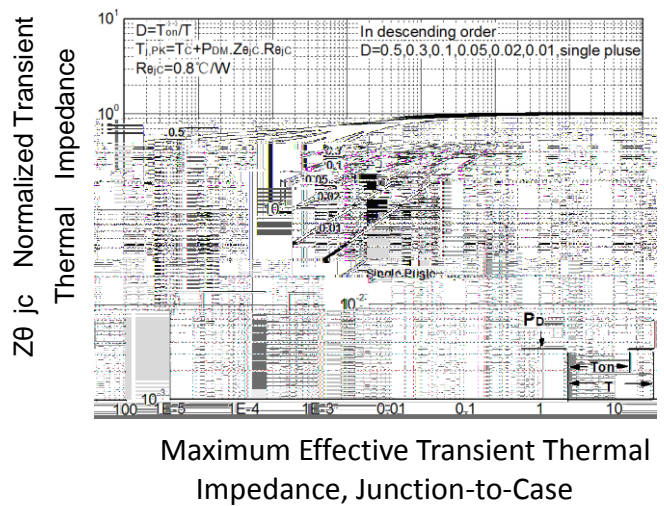
**Figure 2: Drain Current**



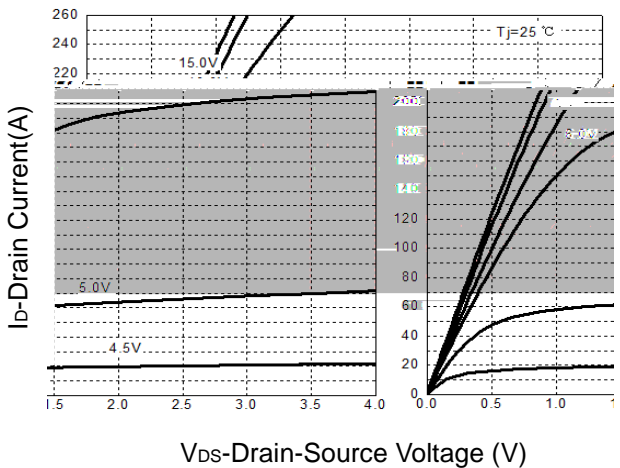
**Figure 3: Safe Operation Area**



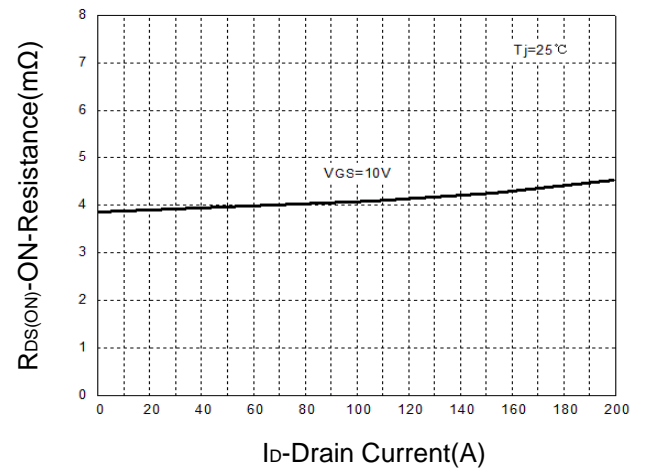
**Figure 4: Thermal Transient Impedance**



**Figure 5: Output Characteristics**



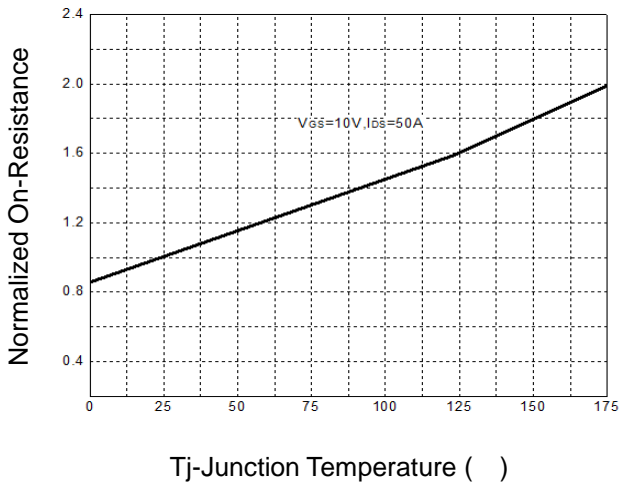
**Figure 6: Drain-Source On Resistance**



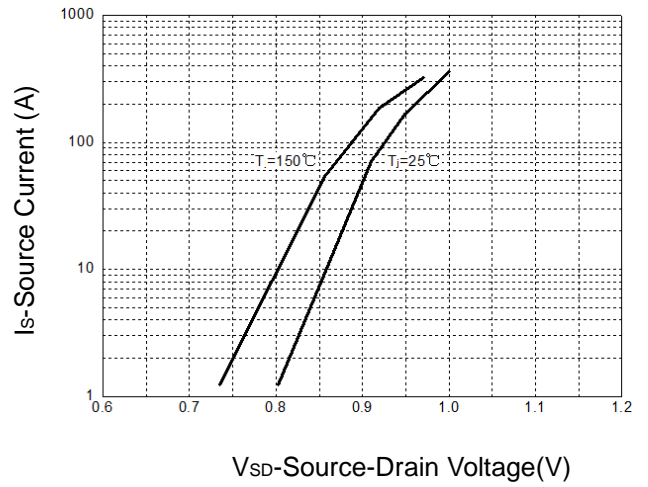
# HYG050N08NS1P/B

## Typical Operating Characteristics(Cont.)

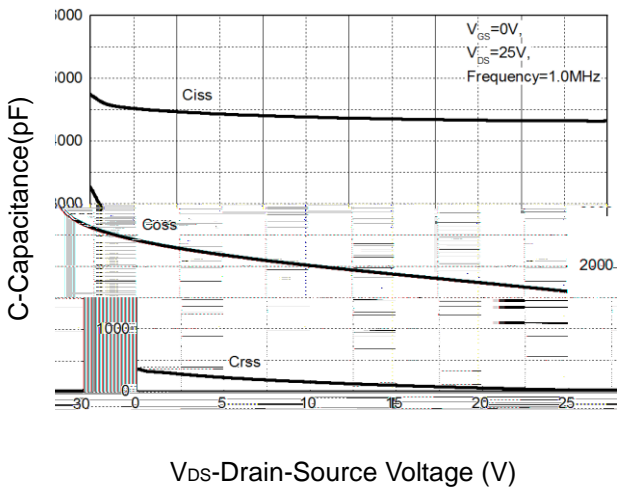
**Figure 7: On-Resistance vs. Temperature**



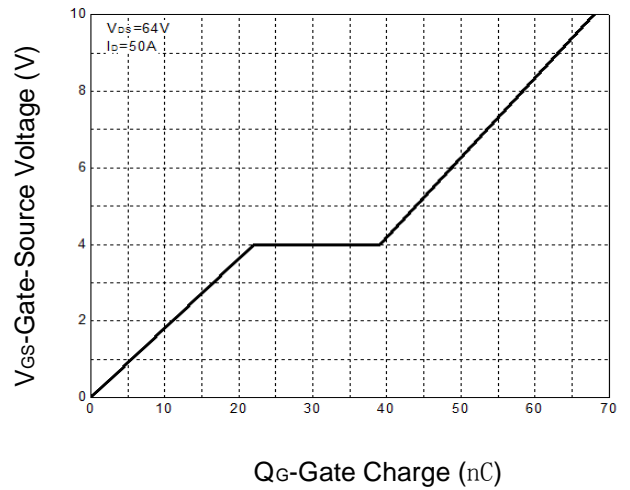
**Figure 8: Source-Drain Diode Forward**



**Figure 9: Capacitance Characteristics**

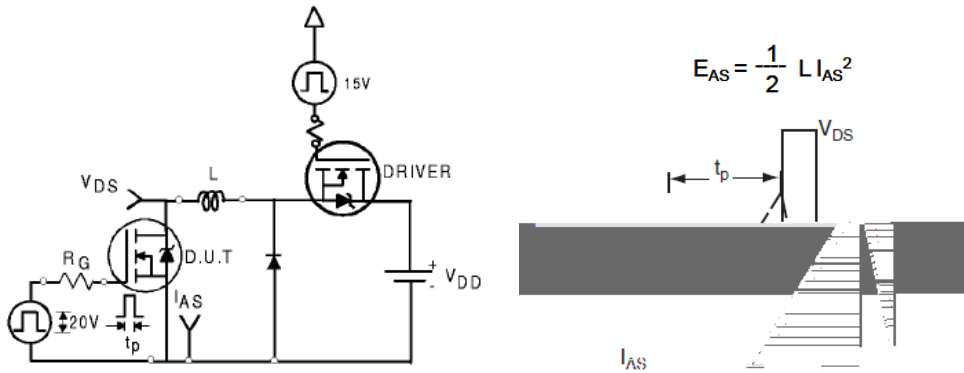


**Figure 10: Gate Charge Characteristics**

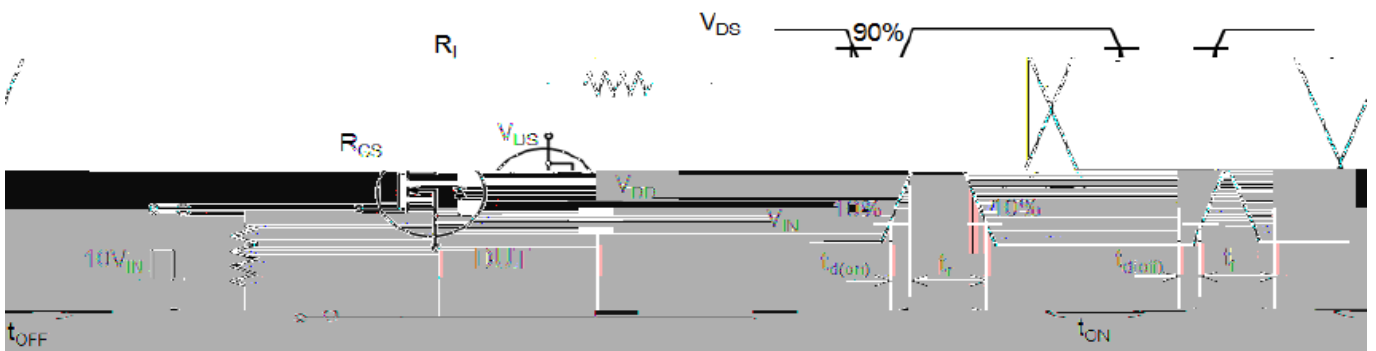


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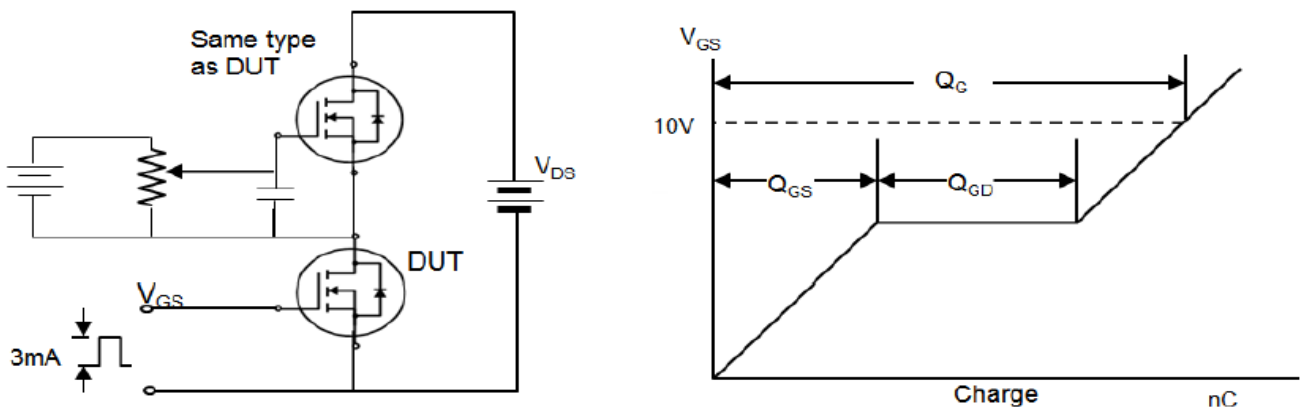
## Avalanche Test Circuit



## Switching Time Test Circuit



## Gate Charge Test Circuit



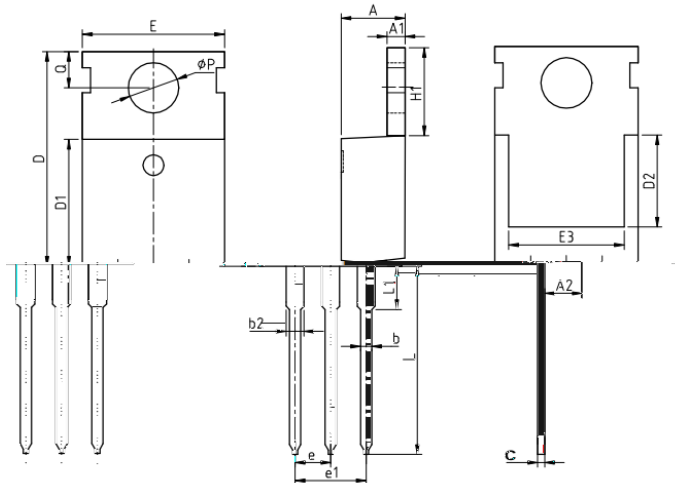
# HYG050N08NS1P/B

## Device Per Unit

Package Type	Unit	Quantity
TO-220FB-3L	Tube	50

## Package Information

### TO-220FB-3L



#### COMMON DIMENSIONS

SYMBOL	mm		
	MIN	NOM	MAX
A	4.37	4.57	4.77
A1	1.25	1.30	1.45
A2	2.20	2.40	2.60
b	0.70	0.80	0.95
b2	1.17	1.27	1.47
c	0.40	0.50	0.65
D	15.10	15.60	16.10
D1	8.80	9.10	9.40
D2	5.50	-	-
E	9.70	10.00	10.30
E3	7.00	-	-
e	2.54 BSC		
e1	5.08 BSC		
H1	6.25	6.50	6.85
L	12.75	13.50	13.80
L1	-	3.10	3.40
ΦP	3.40	3.60	3.80
Q	2.60	2.80	3.00

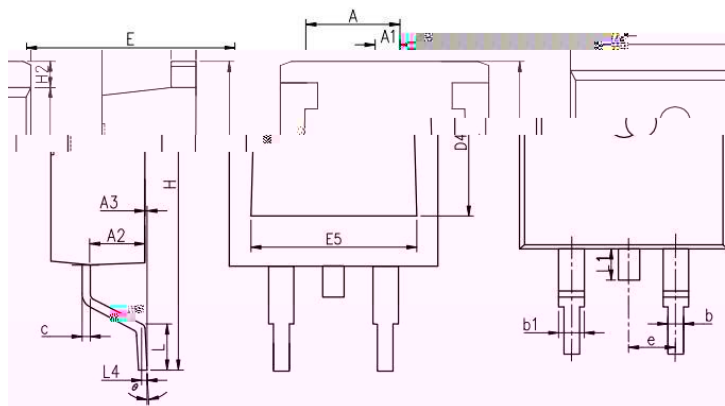
# HYG050N08NS1P/B

## Device Per Unit

Package Type	Unit	Quantity
TO-263-2L	Tube	50

## Package Information

### TO-263-2L



COMMON DIMENSIONS

SYMBOL	mm		
	MIN	NOM	MAX
A	4.37	4.57	4.77
A1	1.22	1.27	1.42
A2	2.49	2.69	2.89
A3	0	0.13	0.25
b	0.7	0.81	0.96
b1	1.17	1.27	1.47
c	0.3	0.38	0.53
D1	8.5	8.7	8.9



## Classification Profile

### Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
<b>Preheat &amp; Soak</b>		
Temperature min ( $T_{smin}$ )	100 °C	150 °C
Temperature max ( $T_{smax}$ )	150 °C	200 °C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds	9 60-120 seconds

<b>Volume mm</b>
<b>350</b>
220 °C
220 °C

<b>Volume mm</b>
<b>2000</b>
260 °C
245 °C

<b>Description</b>
00 Hrs, Bias @ 150°C
tm, 121°C
50°C